

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-41. (Canceled)

42. (Currently Amended) A laminate having a first layer construction of a first inorganic material layer/an insulating layer/a second inorganic material layer or a second layer construction of the inorganic material layer/the first insulating layer, wherein:

said at least the first insulating layer having has a multi-layer structure of including at least a first resin layer and a second resin layer two or more resin layers;

the first resin layer has a first etching rate when etched with an alkali-amine solution and the second resin layer has a second etching rate when etched with the alkali-amine solution; and

a the ratio of the first etching rate to the second etching rate is from of the resin layers being in the range of 6:14:1 to 1:1.

43. (Cancelled)

44. (Previously Presented) The laminate according to claim 42, wherein the insulating layer comprises a core insulating layer and an adhesive layer provided on both sides of the core insulating layer.

45. (Original) The laminate according to claim 44, wherein the strength of bonding of the adhesive layer to the inorganic material layer and the core insulating layer is at least 300 g/cm.

46. (Currently Amended) The laminate according to claim 44, wherein ~~the a~~ thickness ratio of the core insulating layer to each of the adhesive layers is up to 4:1.

47. (Currently Amended) The laminate according to claim 42, wherein at least one of the first resin layer and the second resin layer ~~layers constituting the insulating layer~~ is formed of a polyimide resin.

48. (Currently Amended) The laminate according to claim 42, wherein ~~all the layers constituting each layer of the insulating layer~~ are is formed of a polyimide resin.

49. (Cancelled)

50. (Currently Amended) The laminate according to claim 42, wherein the first inorganic material ~~constituting the laminate~~ is selected from copper, alloy copper, and stainless steel.

51. (Previously Presented) An electronic circuit component produced by etching the laminate according to claim 42.

52. (Previously Presented) An electronic circuit component produced by etching the laminate according to claim 42 by a wet process.

53. (Previously Presented) An electronic circuit component produced by etching the laminate according to claim 42 by a wet process, an inorganic nitride layer and/or an inorganic fluoride layer being absent on the surface of the inorganic material layer exposed by the removal in the etching.

54. (Previously Presented) A suspension for a hard disk drive, produced by etching the laminate according to claim 42 by a wet process, an inorganic nitride layer and/or an inorganic fluoride layer being absent on the surface of the inorganic material layer exposed by the removal in the etching.

55. (Currently Amended) An insulating film comprising ~~two or more resin layers~~ at least a first resin layer and a second resin layer, wherein:

the first resin layer has a first etching rate when etched with an alkali-amine solution and the second resin layer has a second etching rate when etched with the alkali-amine solution; and

the a ratio of the first etching rate to the second etching rate of the resin layers being in the range of is from 6:14:1 to 1:1.

56. (Cancelled)

57. (Currently Amended) The insulating film according to claim 55, wherein at least one of the of the first resin layer and the second resin layers layer is formed of a polyimide resin.

58. (Currently Amended) The insulating film according to claim 55, wherein ~~all the resin layers~~ each layer constituting of the insulating layer are film is formed of a polyimide resin.

59. (Original) A laminate comprising the insulating film according to claim 55 and an inorganic material stacked on top of each other.

60. (Currently Amended) An electronic circuit component produced by etching ~~the a~~ laminate comprising the insulating film according to claim 55 and an inorganic material stacked on top of each other.

61. (Currently Amended) An electronic circuit component produced by etching ~~the a~~ laminate comprising the insulating film according to claim 55 and an inorganic material stacked on top of each other by a wet process.

62. (Currently Amended) An electronic circuit component produced by etching ~~the a~~ laminate comprising the insulating film according to claim 55 and an inorganic material stacked on top of each other by a wet process, an inorganic nitride layer and/or an inorganic fluoride layer being absent on the surface of the inorganic material layer exposed by the etching.

63. (Currently Amended) A suspension for a hard disk drive, produced by etching ~~the~~a laminate comprising the insulating film according to claim 55 and an inorganic material stacked on top of each other by a wet process, an inorganic nitride layer and/or an inorganic fluoride layer being absent on the surface of the inorganic material layer exposed by the etching.